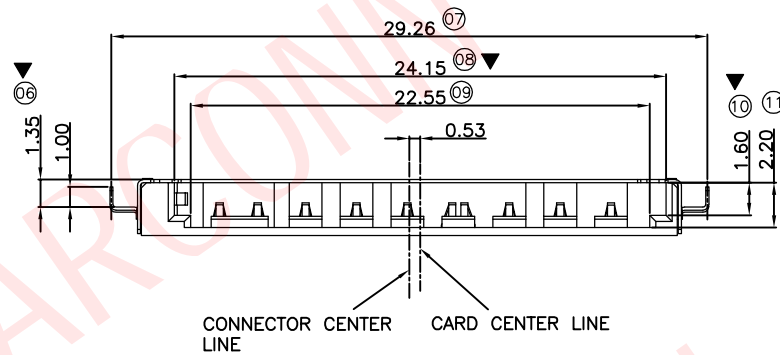
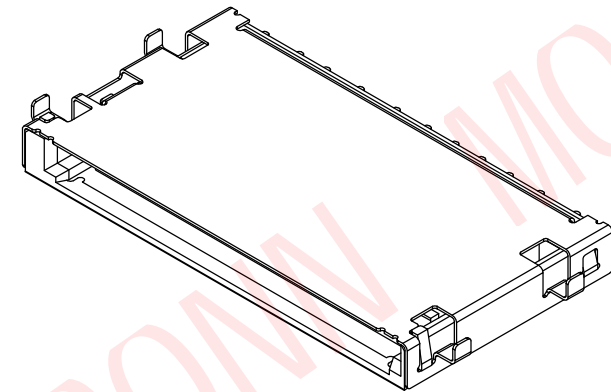
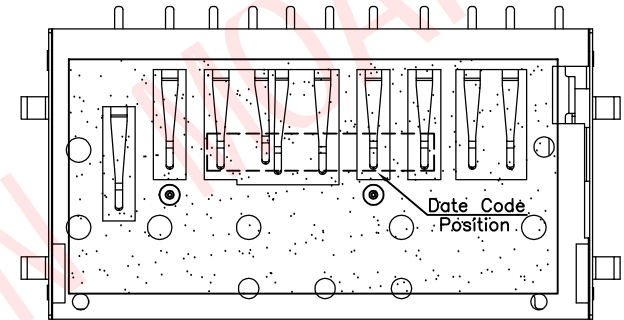
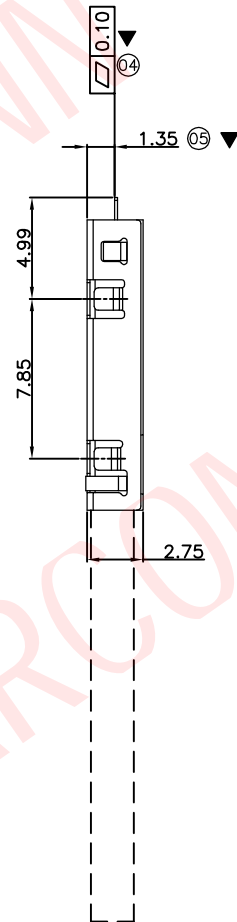
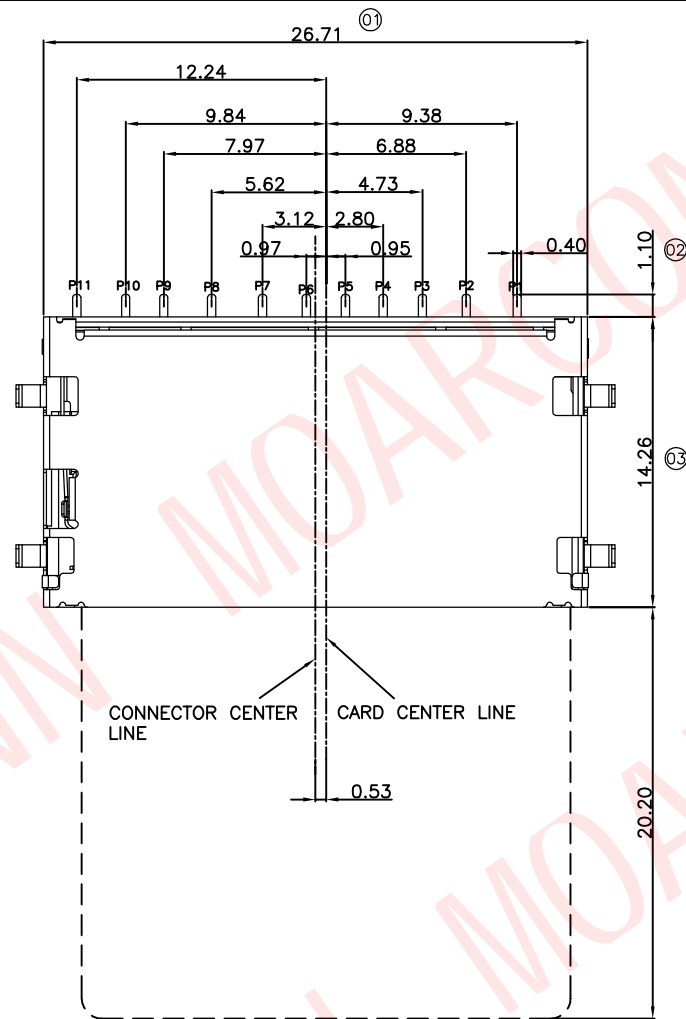


All materials, plating and process meet HF requirements.



MOARCONN
MORE CONNECTIONS SMART FUTURE

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.38
X.XX: ±	0.25
X.XXX: ±	0.10
ANGULAR: ±	3°

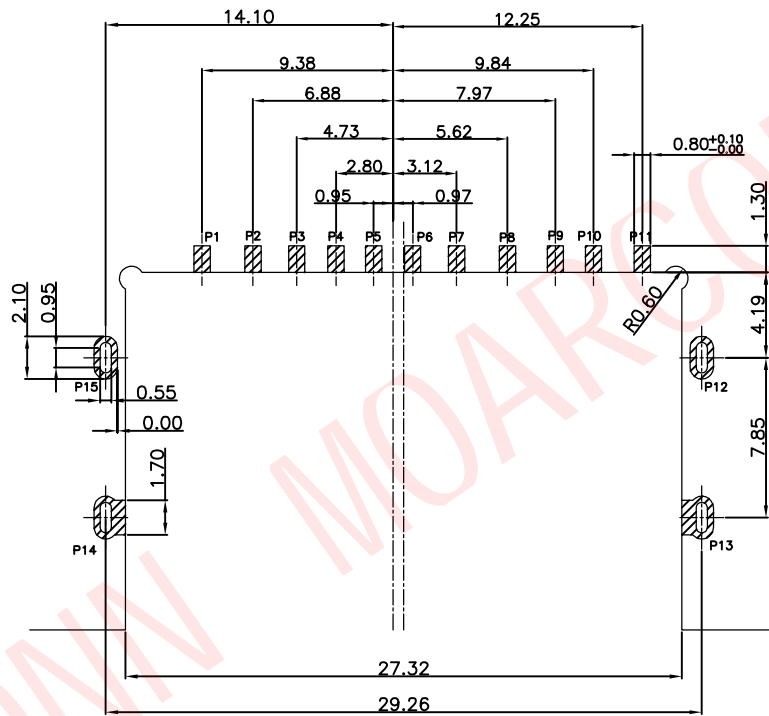
PRODUCT NAME : SDE-B N/P 短型沉板 1.35
PRODUCT NO. : SDE-D1250-11
DRAWING NO. : D-SDE-D1250-11

DRAWING: [Signature]
DATE: 2016.12.25
CHECK: [Signature]
DATE: [Blank]
APPROVED: [Signature]
DATE: [Blank]

SCALE: 1:1
DWG ID: C D
REV.: A
PAGE: 1 OF 2

A	----	NEW RELEASE	ping	2016.12.25
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				

All materials, plating and process meet HF requirements.



RECOMMEND P.C.B LAYOUT
TOLERANCE ±0.05



PAD



No trace , no test point,
no via hole, no ground area

WITHOUT CARD		CARD INSERTED:LOCK		CARD INSERTED:UNLOCK	
W/P	GND	W/P	GND	W/P	GND
C/D	VSS1	C/D	VSS1	C/D	VSS1
	P3		P3		P3

Pin Define

Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		W/P
P12~P15		GND

Specification

*Electrical Characteristics:

Contact Current Rating:0.5 Amperes.
Dielectric Withstanding Voltage:AC500V r.m.s.
Insulation Resistance:1000 MΩ Minimum.
Contact Resistance:100 mΩ Maximum.

*Environmental:

Operating Temperature:-25°C~+85°C.

*Mechanical Characteristics:

Mating Cycles:10,000 Cycles Insertion/Extraction
Card Push Insertion/Out Force:1kgf Maximum.
Contact Retention Force:0.15kgf Minimum.

*Material:

Insulator:HI-Temp Plastic UL 94V-0 Rated.
Contact:Copper Alloy.
Shell:Stainless Steel.

SDE-D1250-11

系列码
SDE:SD CARD

脚型码
D:DIP

流水码

外壳电镀码

00:素材

50:镀镍50u"

端子电镀码

12:端子Au 1u"(G/F)/雾锡

62:端子Au 30u"/雾锡

MOARCONN
MORE CONNECTIONS SMART FUTURE

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT: mm

UNLESS OTHERWISE SPECIFIABLE

DIMENSION TOLERANCE

X.X: ± 0.38
X.XX: ± 0.25
X.XXX: ± 0.10
ANGULAR: ± 3'

PRODUCT NAME : SDE-B N/P 短型沉板 1.35

PRODUCT NO. : SDE-D1250-11

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DATE: 2016.12.25

CHECK:

DATE:

APPROVED:

DATE:

SCALE: 1:1

DWG ID: C D

REV.: A

PAGE: 2 OF 2

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A	----	NEW RELEASE	ping	2016.12.25
1				
2				
3				

PRODUCT NAME :	DRAWING:	DATE:		
SDE-B N/P 短型沉板 1.35		2016.12.25		
PRODUCT NO. :	CHECK:	DATE:		
SDE-D1250-11				
DRAWING NO. :	APPROVED:	DATE:		
D-SDE-D1250-11				
DRAWING NO. :	SCALE:	DWG ID:	REV.:	PAGE:
D-SDE-D1250-11	1:1	C D	A	2 OF 2